

DO NOT SCALE DRAWING

DWG. NO. SD-55358-015

F

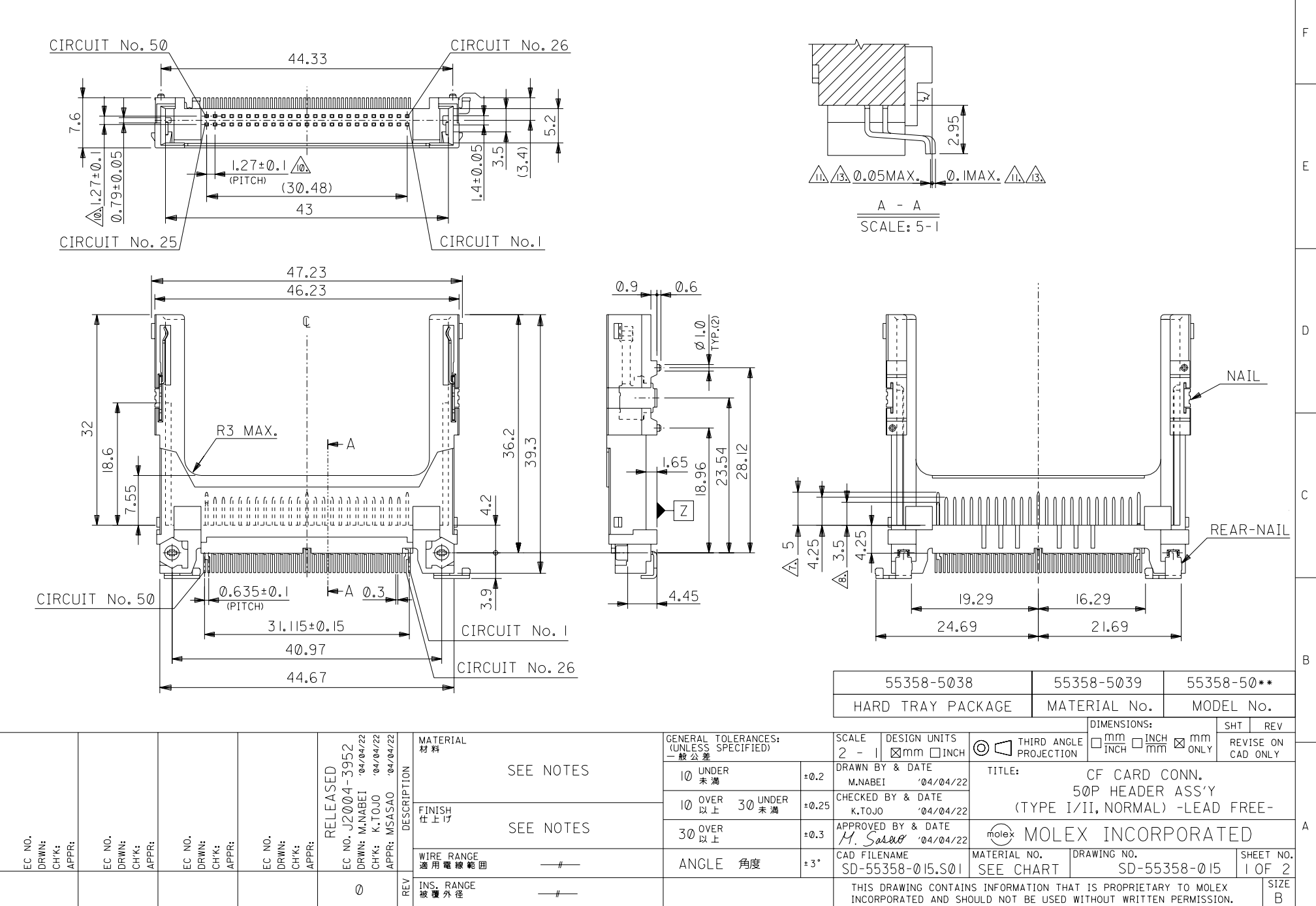
D

V

C

B

A



EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	EC NO. DRWN: CH'K: APPR:	RELEASED EC NO. J2004-3952 DRWN: M.NABEI '04/04/22 CH'K: K.TOJO '04/04/22 APPR: MSASAO '04/04/22	DESCRIPTION MATERIAL 材料 FINISH 仕上り WIRE RANGE 適用電線範囲 INS. RANGE 被覆外径	SEE NOTES SEE NOTES — —	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差 10 UNDER 未満 10 OVER 以上 30 UNDER 未満 30 OVER 以上 ANGLE 角度	±0.2 ±0.25 ±0.3 ±3°	SCALE 2 - 1 DESIGN UNITS M.NABEI '04/04/22 K.TOJO '04/04/22 M. Sasao '04/04/22 CAD FILENAME SD-55358-015.S01	THIRD ANGLE PROJECTION TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE- MOLEX INCORPORATED	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY	SHT REVISE ON CAD ONLY	SHEET NO. 1 OF 2
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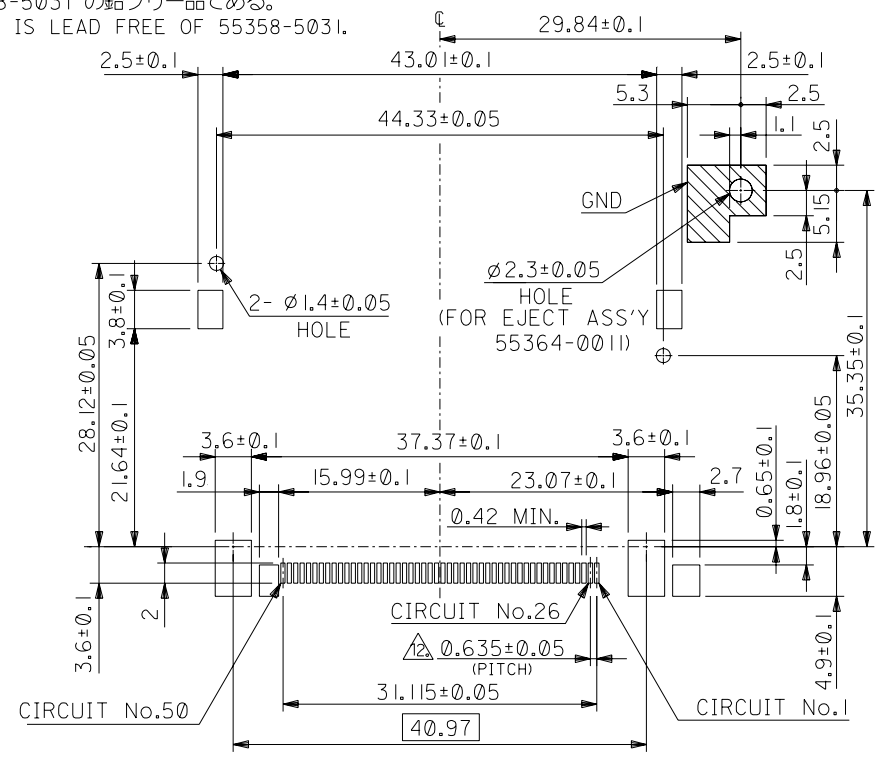
C

B

DO NOT SCALE DRAWING

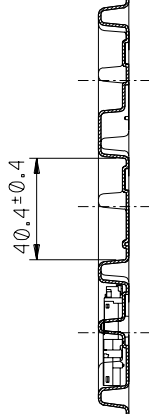
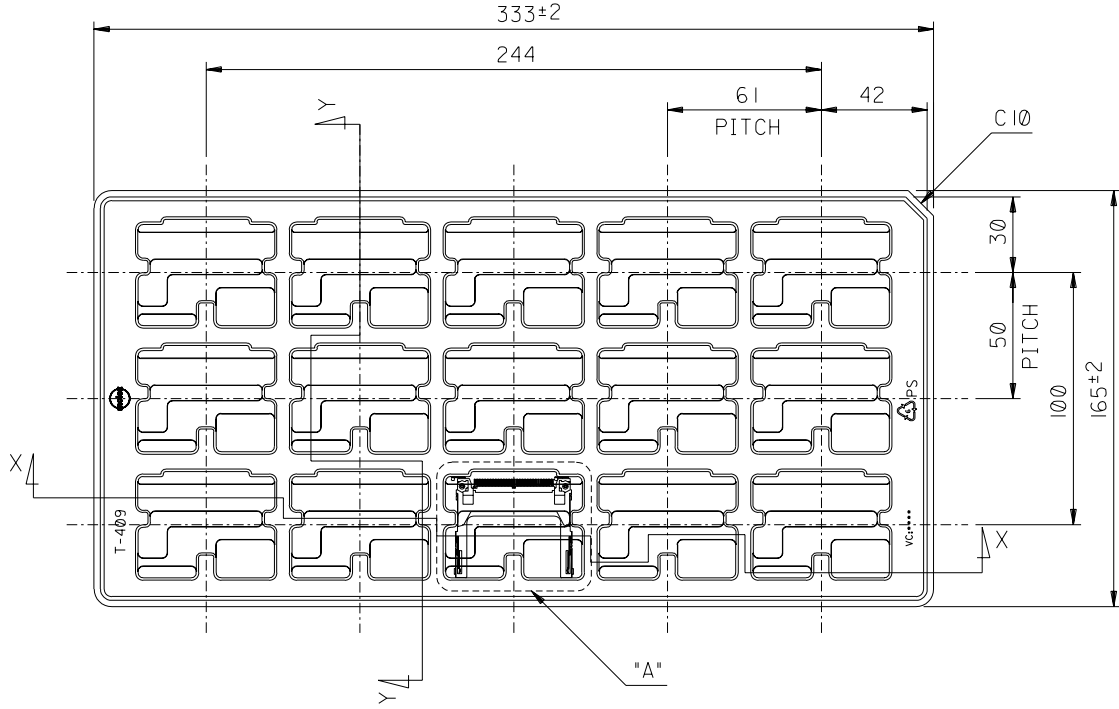
- 注) 1. 材質 MATERIAL
ハウジング: ガラス入りLCP UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
ピン: リン青銅
PIN: PHOSPHOR BRONZE
ネール: リン青銅 (t0.3)
NAIL: PHOSPHOR BRONZE (t0.3)
リヤネール: リン青銅 (t0.48)
REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING
ピン
接点部: 金メッキ
CONTACT AREA: GOLD
半田付け部: 錫メッキ
SOLDER TAIL AREA: TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
ネール
接点部: 金メッキ
CONTACT AREA: GOLD
半田付け部: 錫メッキ
SOLDER TAIL AREA: TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
リヤネール
錫メッキ
REAR-NAIL
TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚: t=0.8 MIN.
RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1
RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒
HOUSING COLOR: BLACK
7. 寸法適用極: 1,13,38,50
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
8. 寸法適用極: 25,26
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。
THIS DIMENSION TO BE MEASURED AT PIN BASE.

11. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDERTAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDERTAILS TIP.
12. 公差非累積
NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5031 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55358-5031.

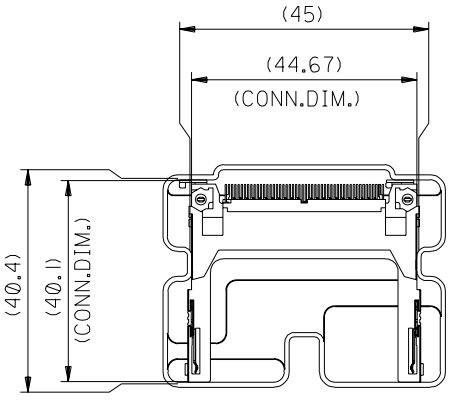


基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		DESCRIPTION SEE SHEET 1 OF 2	MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		55358-50**		MODEL NO.		DIMENSIONS:		SHT	REV					
													SEE NOTES			SCALE 2 - 1	DESIGN UNITS ☒ mm ☐ INCH		THIRD ANGLE PROJECTION	☐ mm INCH	☐ INCH mm	☒ mm ONLY	REVISE ON CAD ONLY						
																10 UNDER 未満	±0.2		DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-								
																10 OVER 以上	30 UNDER 未満		±0.25	CHECKED BY & DATE K.TOJO '04/04/22									
												30 OVER 以上	±0.3	APPROVED BY & DATE M. Sasa '04/04/22		MOLEX INCORPORATED													
													WIRE RANGE 適用電線範囲	— # —		ANGLE 角度		±3°	CAD FILENAME SD-55358-015.S02		MATERIAL NO. — # —		DRAWING NO. SD-55358-015		SHEET NO. 2				
													REV	INS. RANGE 被覆外径		— # —		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.										SIZE B	



SECT. Y-Y



DETAIL A
(SCALE 1-1)

NOTES

1. 一般公差: ±0.5
GENERAL TOLERANCES: ±0.5
2. 反り: 2MAX.
WARP: 2MAX.
3. 梱包数: 15個
PACKAGING QUANTITY: 15PCS.
4. 本製品は 55358-5026/-5036 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55358-5026/-5036.

SECT. X-X

164NO. DRWN: CH'K: APPR:		163NO. DRWN: CH'K: APPR:		162NO. DRWN: CH'K: APPR:		161NO. DRWN: CH'K: APPR:		RELEASED 2004-3952 DRWN: M.NABEI CH'K: K.TOJO APPR: M.SASAO		MATERIAL 材料 POLYSTYRENE (t=1.0)		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 1:2 DESIGN UNITS mm INCH		MODEL NO. 2004-3952 PROJECTION		DIMENSIONS: mm INCH mm ONLY		SHT REV	
								DESCRIPTION		FINISH 仕上げ		10 UNDER 未満		DRAWN BY & DATE M.NABEI '04/04/22		TITLE: TRAY FOR CF CARD CONN. 50P HEADER HS'G ASS'Y -LEAD FREE-					
												10 OVER 30 UNDER 以上 未満		CHECKED BY & DATE K.TOJO '04/04/22							
												30 OVER 以上		APPROVED BY & DATE M.SASAO '04/04/22		MOLEX MOLEX INCORPORATED					
												ANGLE 角度		CAD FILENAME SD-55358-016.S01		MATERIAL NO. SEE CHART		DRAWING NO. SD-55358-016		SHEET NO. 1 OF 1	
								REV		INS. RANGE 被覆外径										SIZE B	